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DMC364A5

Silicon NPN epitaxial planar type (Tr1)

Silicon NPN epitaxial planar type (Tr2)

For digital circuits

Marking Symbol : L0

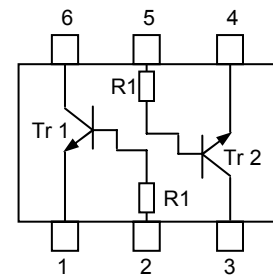
Package Code : SSSMini6-F2-B

Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	VCBO	50	V
	Collector-emitter voltage (Base open)	VCEO	50	V
Tr2	Collector current	IC	80	mA
Overall	Total power dissipation *1	PT	125	mW
	Junction temperature	Tj	150	$^\circ\text{C}$
	Storage temperature	Tstg	-55 to +150	$^\circ\text{C}$

Note: 1. *1 Measuring on substrate at 17 mm × 10 mm × 1 mm

Internal Connection



Resistance value	R1	10	k Ω

Pin name

1. Emitter(Tr1)	4. Emitter(Tr2)
2. Base(Tr1)	5. Base(Tr2)
3. Collector(Tr2)	6. Collector(Tr1)

Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Parameter		Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)		VCBO	IC = 10 μA , IE = 0	50			V
Collector-emitter voltage (Base open) *1		VCEO	IC = 2 mA, IB = 0	50			V
Collector-base cutoff current (Emitter open)		ICBO	VCB = 50 V, IE = 0			0.1	μA
Collector-emitter cutoff current (Base open)		ICEO	VCE = 50 V, IB = 0			0.5	μA
Emitter-base cutoff current (Collector open)		IEBO	VEB = 6 V, IC = 0			0.01	mA
Forward current transfer ratio		hFE	VCE = 10 V, IC = 5 mA	160		460	-
Collector-emitter saturation voltage		VCE(sat)	IC = 10 mA, IB = 0.5 mA			0.25	V
Input voltage		Vi(on)	VCE = 0.2 V, IC = 5 mA	1.2			V
		Vi(off)	VCE = 5 V, IC = 100 μA			0.4	
Input resistance		R1		-30%	10	+30%	k Ω

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. *1 Pulse measurement

Packing

Embossed type (Thermo-compression sealing) R specification : 10 000 pcs / reel

2010.3.11	2010.1125	
Prepared	Revised	

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